

date 08/05/2022

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# MODEL: HSB25-282810 | DESCRIPTION: HEAT SINK

#### **FEATURES**

- BGA design
- small footprint
- top mount
- aluminum alloy





#### **MODEL** thermal resistance<sup>1</sup> power dissipation<sup>1</sup> @ 75°C ∆T, nat @ 1 W, @ 1W, @ 1 W, @ 75°C ∆T, nat 400 LFM conv (°C/W) nat conv 200 LFM conv (°C/W) $(^{\circ}C/W)$ (°C/W) (W) 15.41 18.2 5.1 3.0 4.87 HSB25-282810

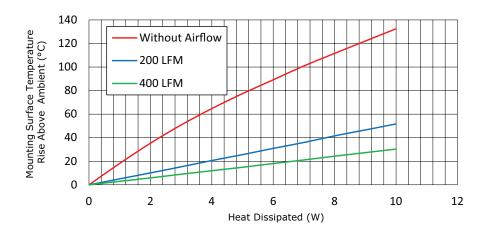
Note:

1. See performance curves for full thermal resistance details.

## PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	18.2	5.1	3.0
2	35.3	10.1	5.9
3	50.8	15.3	9.0
4	64.7	20.6	12.0
5	77.4	25.6	14.9
6	89.1	30.9	18.1
7	100.9	35.9	21.1
8	111.5	41.5	24.3
9	122.0	46.5	27.3
10	132.4	51.6	30.3



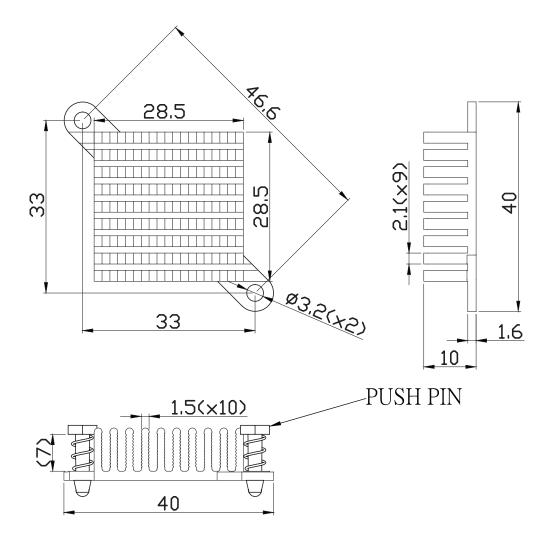


# **MECHANICAL DRAWING**

units: mm

tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	13.9 g



### **REVISION HISTORY**

rev.	description	date
1.0	initial release	04/15/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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